

34. (new) The method of claim 32, wherein said pattern in said second test area comprises a bar-in-bar pattern.

35. (new) The apparatus of claim 16, wherein the metrology target further includes a second pattern built into layers A and B, and wherein the optical instrument further includes a camera disposed to observe said second pattern and obtain measurements therefrom of any gross overlay errors, said processor connected to also receive said measurements from said camera.

36. (new) The apparatus of claim 35, wherein said second pattern comprises a box-in-box pattern.

37. (new) The apparatus of claim 35, wherein said second pattern comprises a bar-in-bar pattern.

38. (new) The apparatus of claim 24, wherein the metrology target further includes a second pattern built into layers A and B, and wherein the apparatus further includes a camera disposed to observe said second pattern and obtain measurements therefrom of any gross overlay errors, said processor connected to also receive said measurements from said camera.

39. (new) The apparatus of claim 38, wherein said second pattern comprises a box-in-box pattern.

40. (new) The apparatus of claim 38, wherein said second pattern comprises a bar-in-bar pattern.